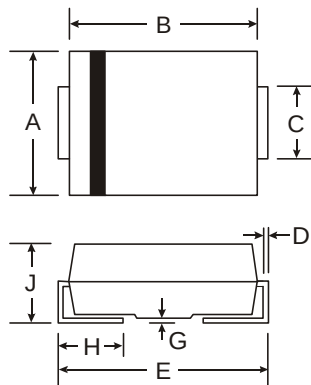


Features

- Guard Ring Die Construction for Transient Protection
- Ideally Suited for Automatic Assembly
- Low Power Loss, High Efficiency
- For Use in Low Voltage, High Frequency Inverters, Free Wheeling, and Polarity Protection Application
- Lead Free Finish/RoHS Compliant (Note 1)
- Green Molding Compound (No Halogen and Antimony)(Note 2)

Notes: 1. EU Directive 2002/95/EC (RoHS). All applicable RoHS exemptions applied, see EU Directive 2002/95/EC Annex Notes.

2. Product manufactured with Data Code 0924 (week 24, 2009) and newer are built with Green Molding Compound.



SMC		
Dim	Min	Max
A	5.59	6.22
B	6.60	7.11
C	2.75	3.18
D	0.15	0.31
E	7.75	8.13
G	0.10	0.20
H	0.76	1.52
J	2.00	2.62
All Dimensions in mm		

Mechanical Data

Case: SMC

Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0

Moisture Sensitivity: Level 1 per J-STD-020

Terminals: Lead Free Plating (Matte Tin Finish).

Solderable per MIL-STD-202, Method 208

Polarity: Cathode Band or Cathode Notch

Weight: 0.21 grams (approximate)

Maximum Ratings and Thermal Characteristics

@ TA = 25°C unless otherwise specified Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	B520C	B530C	B540C	B550C	B560C	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	20	30	40	50	60	V
Working Peak Reverse Voltage	V _{RWM}						
DC Blocking Voltage	V _R						
RMS Reverse Voltage	V _{R(RMS)}	14	21	28	35	42	V
Average Rectified Output Current @ T _T = 90°C	I _O	5.0					A
Non-Repetitive Peak Forward Surge Current, 8.3 ms single half-sine-wave Superimposed on Rated Load	I _{FSM}	100					A
Typical Thermal Resistance, Junction to Terminal (Note 3)	R _{θJT}	10					K/W
Typical Thermal Resistance, Junction to Ambient	R _{θJA}	50					°C/W
Operating Temperature Range	T _j	-55 to +125					°C
Storage Temperature Range	T _{STG}	-55 to +150					°C

RATINGS AND CHARACTERISTIC CURVES

Electrical Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Forward Voltage Drop B520C, B530C, B540C B550C, B560C	V_F	-	-	0.55 0.70	V	$I_F = 5.0\text{A}$, $T_A = 25^\circ\text{C}$
Leakage Current (Note 5)	I_R	-	-	0.5 20	mA	@ Rated V_R , $T_A = 25^\circ\text{C}$ @ Rated V_R , $T_A = 100^\circ\text{C}$
Total Capacitance	C_T	-	-	300	pF	$V_R = 4\text{V}$, $f = 1\text{MHz}$

Notes: 3. Thermal Resistance: Junction to ambient, unit mounted on PC board with 8.0 mm^2 (0.033 mm thick) copper pads as heat sink.
4. Short duration pulse test used to minimize self-heating effect.

Fig. 1 Typical Forward Characteristics

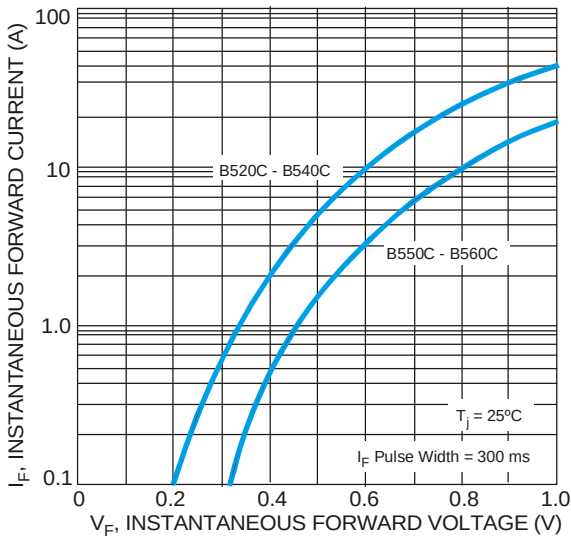


Fig. 2 Typical Reverse Characteristics

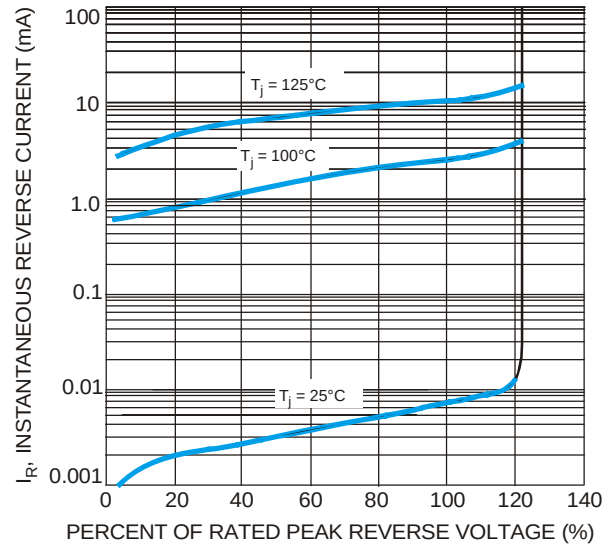


Fig. 3 Total Capacitance vs. Reverse Voltage

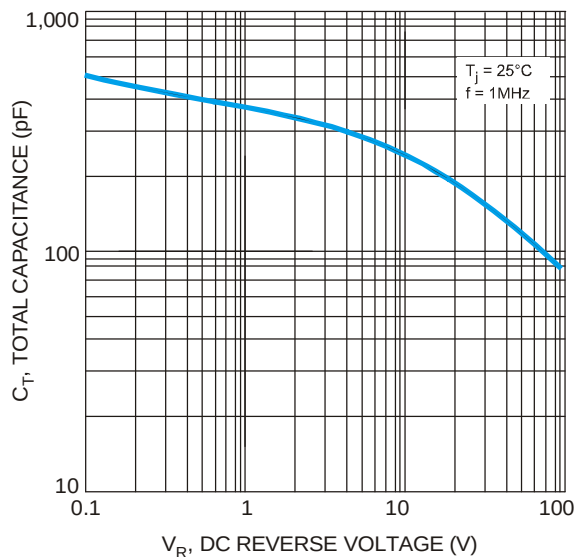
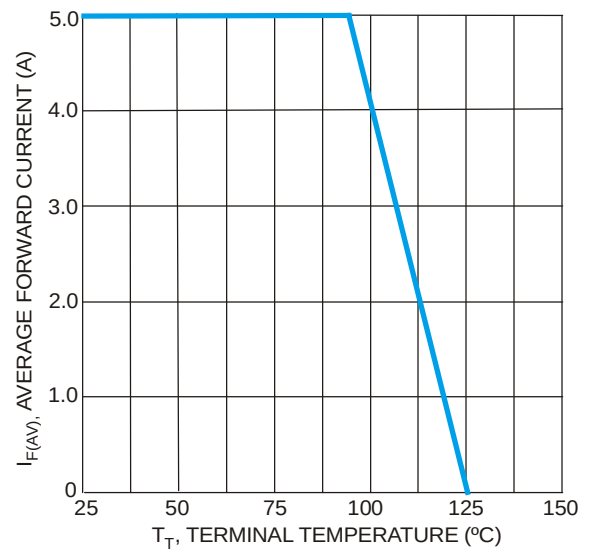


Fig. 4 Forward Current Derating Curve



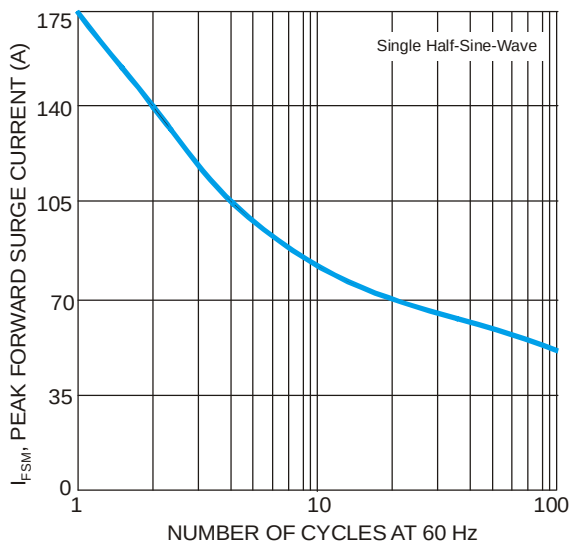


Fig. 5 Max Non-Repetitive Peak Forward Surge Current